

Title (en)
ELECTRICAL INSULATION SYSTEM WITH IMPROVED ELECTRICAL BREAKDOWN STRENGTH

Title (de)
ELEKTRISCHES ISOLATIONSSYSTEM MIT VERBESSERTER ELEKTRISCHER DURCHSCHLAGSSTÄRKE

Title (fr)
SYSTÈME D'ISOLATION ÉLECTRIQUE À RÉSISTANCE ACCRUE AU CLAQUAGE ÉLECTRIQUE

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EP 2195813 A1 20100616 (EN)

Application
EP 07820881 A 20071003

Priority
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Abstract (en)
[origin: WO2009043376A1] Electrical insulation system with improved electrical breakdown strength, said electrical insulation system comprising a hardened polymer component having incorporated therein a conventional filler material and a selected pretreated filler material, wherein (a) the hardened polymer component is selected from epoxy resin systems, polyesters, polyamides, polybutylene terephthalate, polyurethanes and polydicyclopentadiene; (b) the conventional filler material is a known filler material having an average grain size distribution within the range of 1 µm- 500 µm, being present in a quantity within the range of 40 %- 65 % by weight, calculated to the total weight of the insulator system; and (c) the selected pretreated filler material is selected from silica, quartz, or a silicate, or is a mixture of these compounds, having an average grain size distribution within the range of 1 µm-500 µm, wherein said selected filler material has been pretreated with an intercalating compound and wherein said pretreated filler material is present in an amount of 1 %-30 % by weight, calculated to the weight of the conventional filler material present in the insulator system.

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